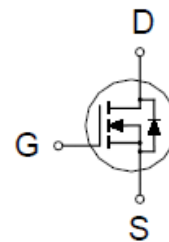
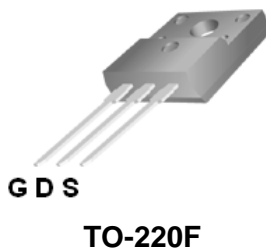


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PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
200V	150mΩ @ $V_{GS} = 10V$	18A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	200	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	I_D	18	A
	$T_C = 100\text{ }^\circ\text{C}$		7	
Pulsed Drain Current ¹		I_{DM}	30	
Avalanche Current		I_{AS}	11	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	61	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	42	W
	$T_C = 100\text{ }^\circ\text{C}$		17	
Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		3	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS		
			MIN	TYP	MAX			
STATIC								
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	200			V		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	2	3			
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200V, V _{GS} = 0V			1	μA		
		V _{DS} = 160V, V _{GS} = 0V, T _J = 125 °C			10			
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 9A		117	150	mΩ		
		V _{GS} = 4.5V, I _D = 9A		175	195			
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 9A		15		S		
DYNAMIC								
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz		811		pF		
Output Capacitance	C _{oss}			137				
Reverse Transfer Capacitance	C _{rss}			19				
Total Gate Charge ²	Q _{g(VGS=10V)}	V _{DS} = 160V, I _D = 18A		25		nC		
	Q _{g(VGS=4.5V)}			13				
Gate-Source Charge ²	Q _{gs}			3				
Gate-Drain Charge ²	Q _{gd}			10				
Turn-On Delay Time ²	t _{d(on)}		V _{DS} = 100V, I _D ≅ 18A, V _{GS} = 10V, R _{GEN} = 25Ω		21			nS
Rise Time ²	t _r				140			
Turn-Off Delay Time ²	t _{d(off)}			183				
Fall Time ²	t _f			133				
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)								
Continuous Current	I _S				18	A		
Forward Voltage ¹	V _{SD}	I _F = 18A, V _{GS} = 0V			1	V		
Reverse Recovery Time	t _{rr}	I _F = 18A, dI _F /dt = 100A/μs		130		nS		
Reverse Recovery Charge	Q _{rr}			0.67		uC		

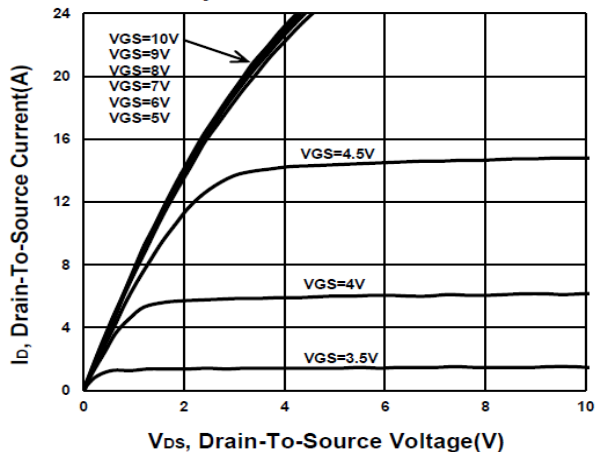
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

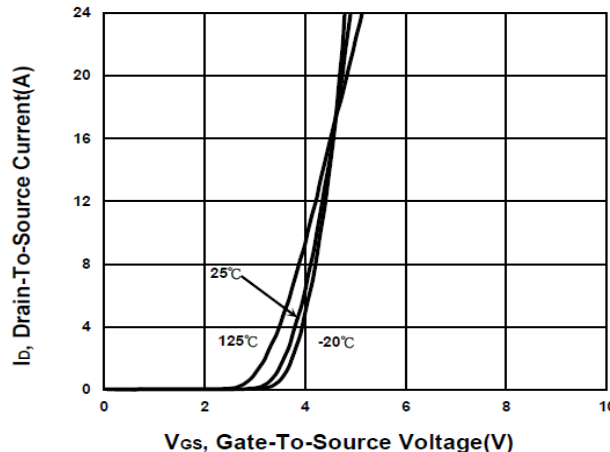
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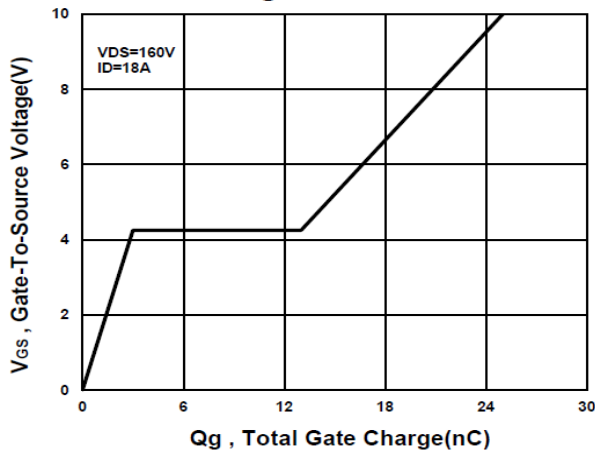
Output Characteristics



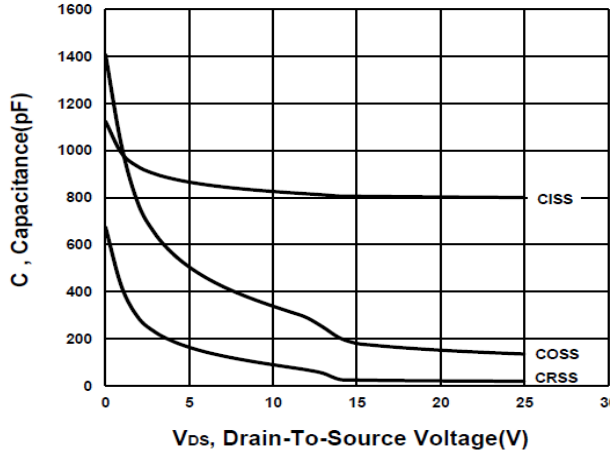
Transfer Characteristics



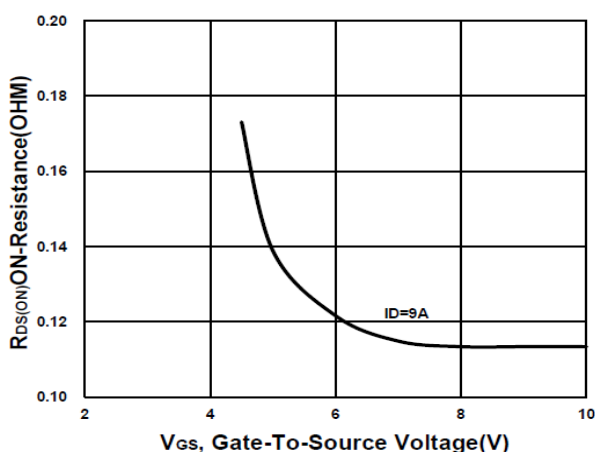
Gate charge Characteristics



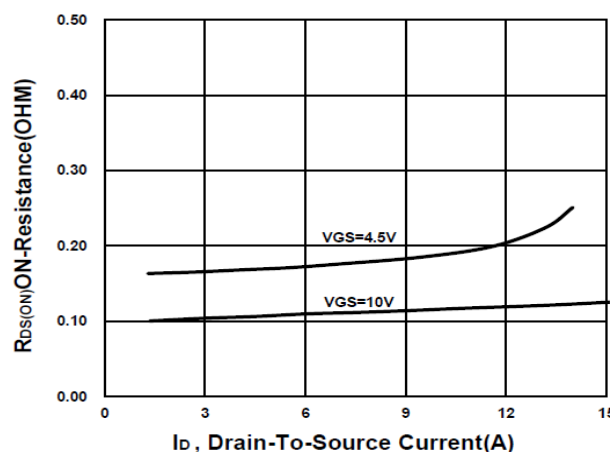
Capacitance Characteristic



On-Resistance VS Gate-To-Source



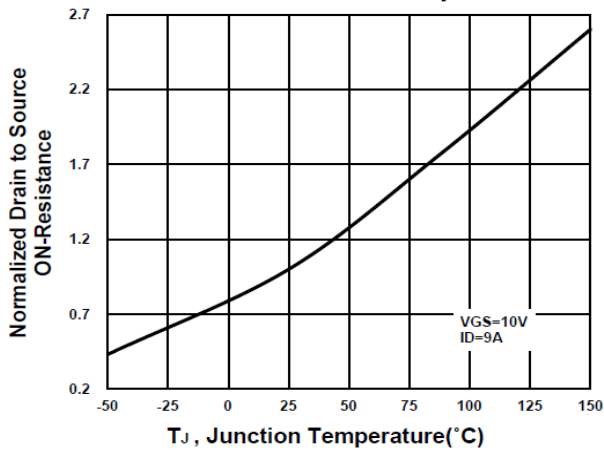
On-Resistance VS Drain Current



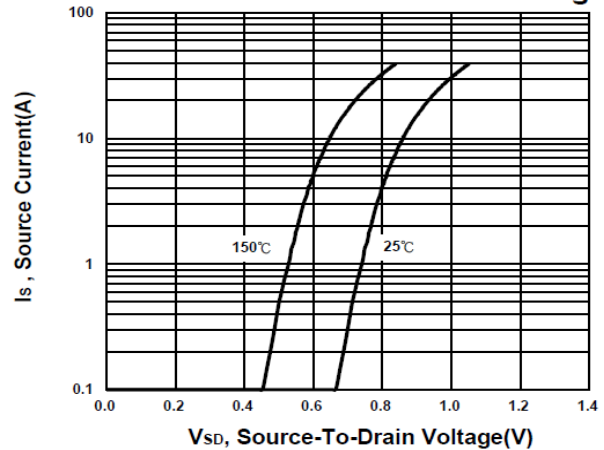
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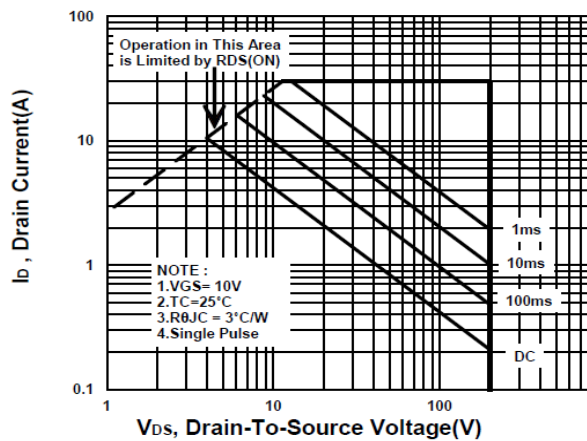
On-Resistance VS Temperature



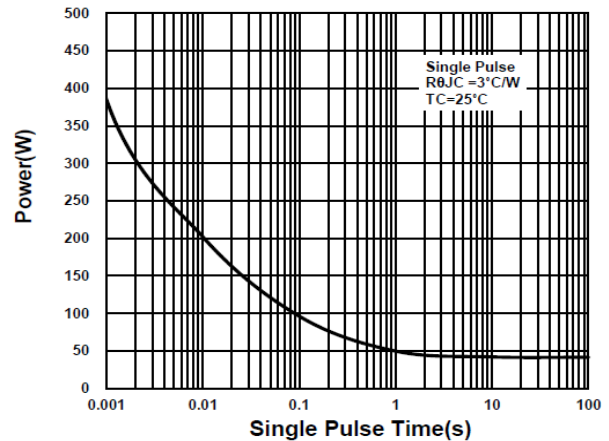
Source-Drain Diode Forward Voltage



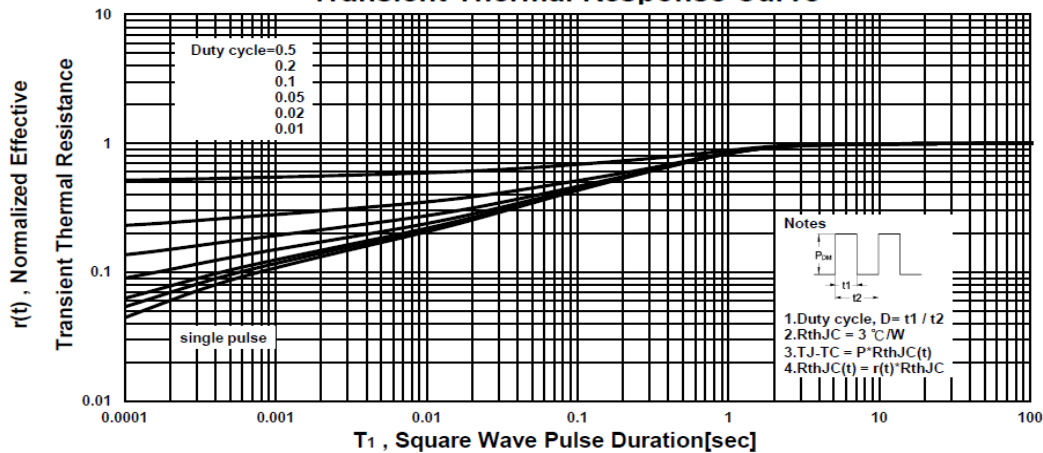
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



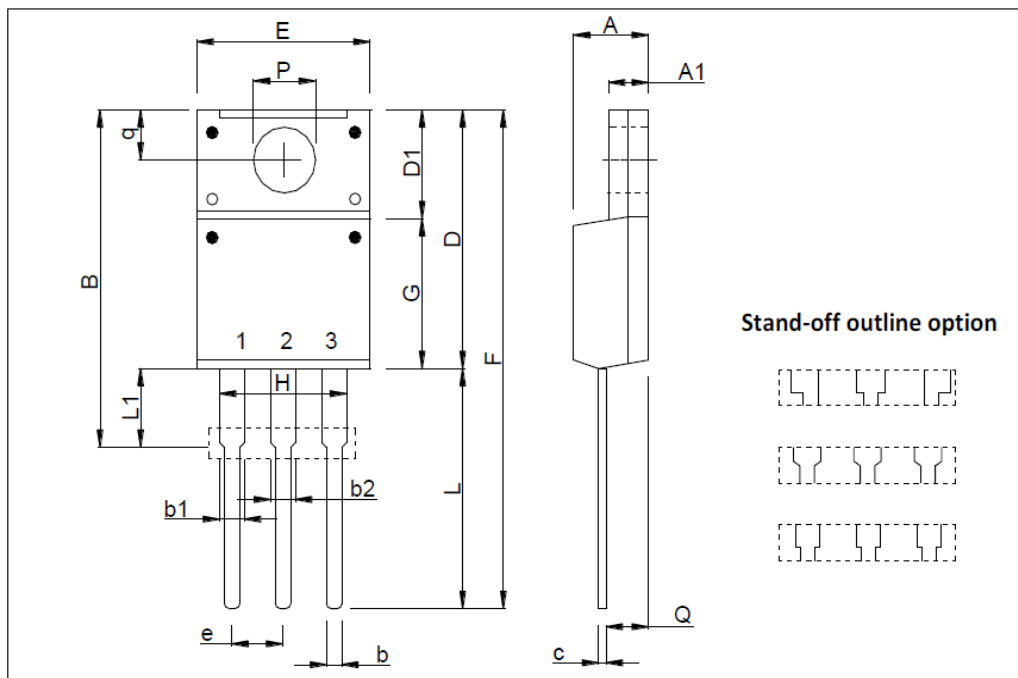
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Package Dimension

TO-220F (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.4		4.93	e	2.34		2.74
A1	2.34		3.1	F	27.2		30.6
B	18.8		20	G	7.7		9.39
b	0.65		1	H	6.18		6.82
b1	0.93		1.6	L	12.7		14.2
b2	0.95		1.6	L1	2.88		3.7
c	0.4		1	P	2.98		3.7
D	13.5		16.4	Q	2.3		2.96
D1	6.48		6.95	q	3.1		3.8
E	9.8		10.4				

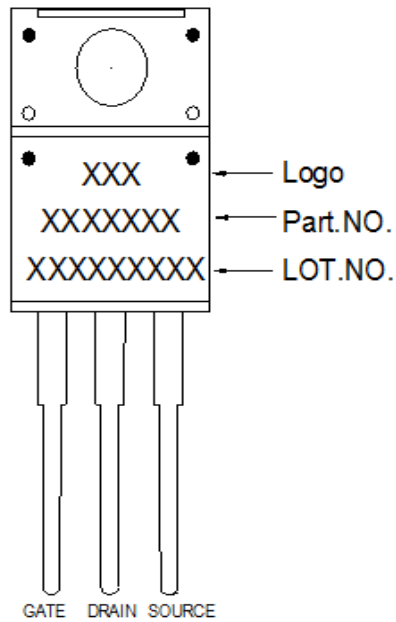


*因各家封装模具不同而外观略有所差异，不影响电性及Layout。

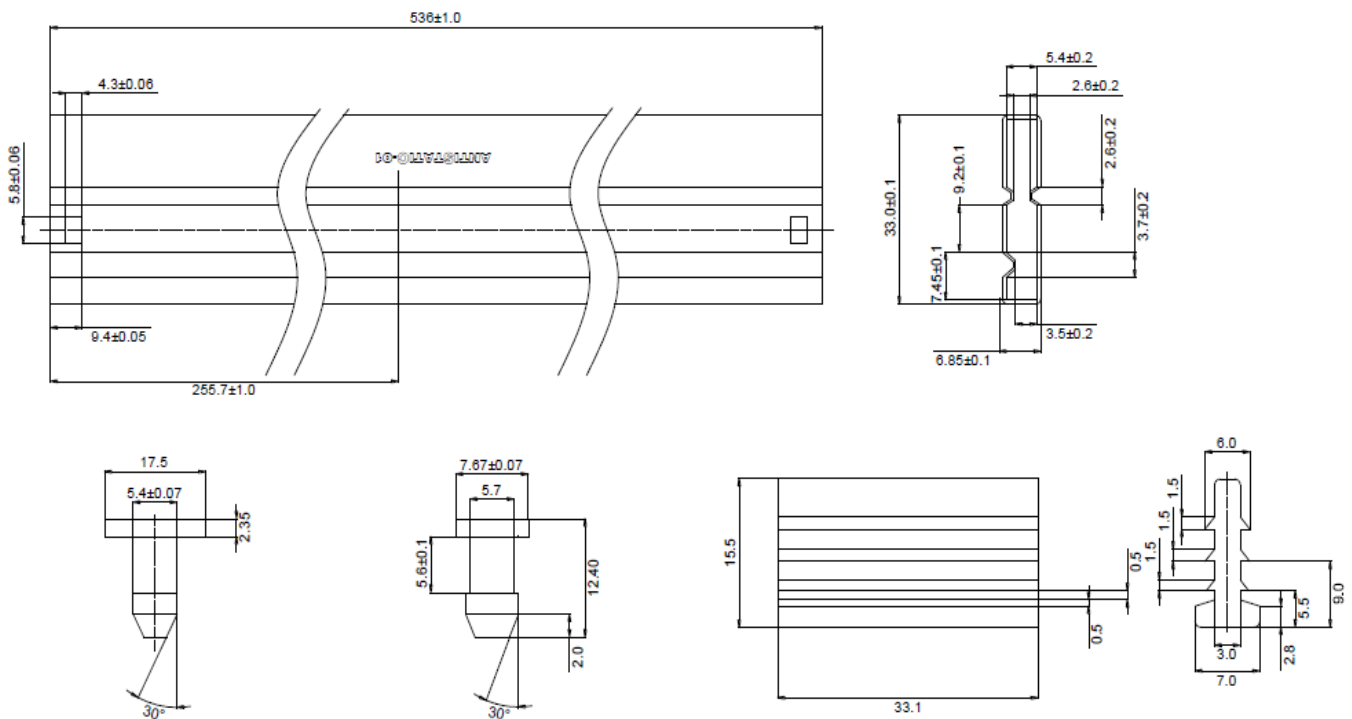
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A. Marking Information



B. Tape & Reel Information: 50pcs/Tube (2000pcs/Box)

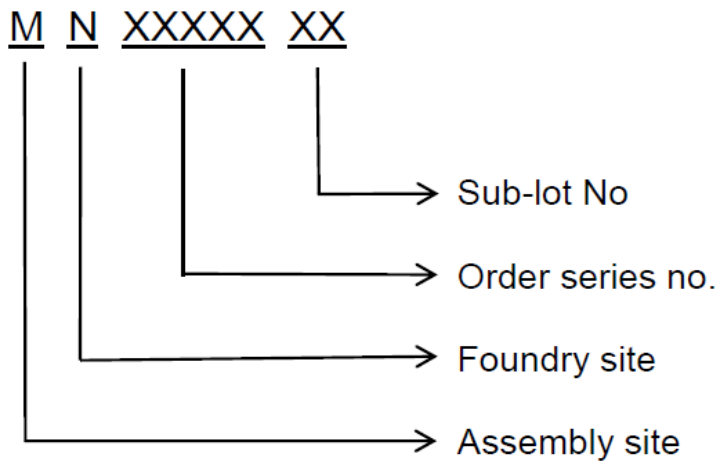


P1820HTFB

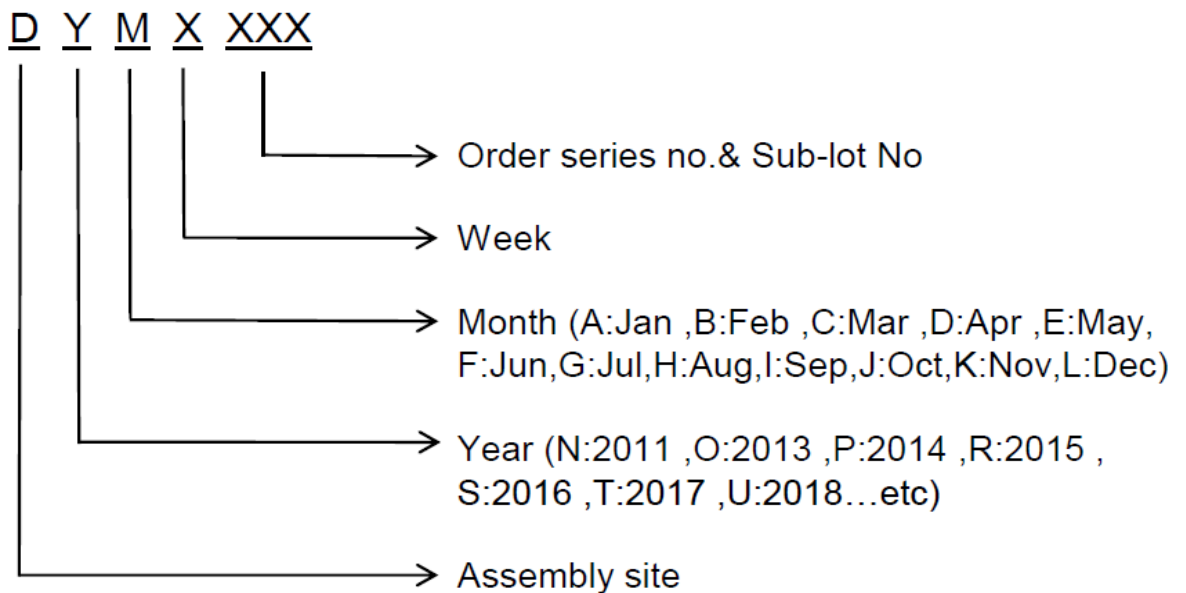
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C. Lot No.&Date Code rule

1.Lot No.



2.Date Code





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D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least